

4-Channel 1-Wire LED Driver in 3x3mm Package



FEATURES

- Drives up to 4 LED channels
- 1-wire EZDim™ Programmable LED Current
- Accurate 1mA Dimming Level
- Power efficiency up to 91%
- Fractional pump 1x/1.5x
- Low noise input ripple
- Fixed High Frequency Operation 1MHz
- “Zero” Current Shutdown Mode
- Soft start and current limiting
- Short circuit protection
- Thermal shutdown protection
- 12-lead TDFN 3mm x 3mm package

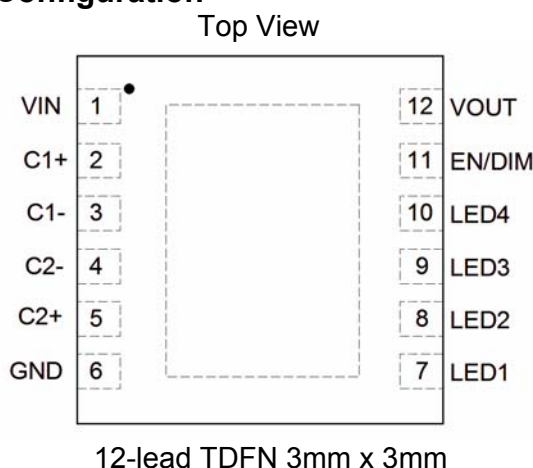
APPLICATIONS

- LCD Display Backlight
- Cellular Phones
- Digital Still Cameras
- Handheld Devices

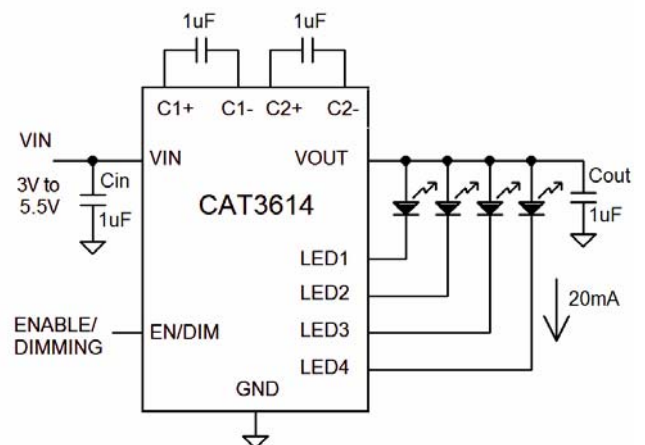
ORDERING INFORMATION

Part Number	Package	Quantity per Reel	Package Marking
CAT3614HS2-T2	TDFN-12 3x3	2000	HAAB
CAT3614HV2-T2	TDFN-12 3x3 Green	2000	HAAA

Pin Configuration



Typical Application Circuit



Note: Unused LED channels must be connected to VOUT.

ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Unit
VIN, LEDx voltage	6	V
VOUT, C1±, C2± voltage	7	V
EN/DIM voltage	VIN + 0.7V	V
Storage Temperature Range	-65 to +160	°C
Junction Temperature Range	-40 to +125	°C
Lead Temperature	300	°C

RECOMMENDED OPERATING CONDITIONS

Parameter	Range	Unit
VIN	3 to 5.5	V
Ambient Temperature Range	-40 to +85	°C
ILED per LED pin	0 to 31	mA
Total Output Current	0 to 124	mA

Typical application circuit with external components are shown on page 1.

ELECTRICAL OPERATING CHARACTERISTICS (over recommended operating conditions unless specified otherwise) VIN = 3.6V, EN = High, ambient temperature of 25°C.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
IQ	Quiescent Current	1x mode, no load	0.3	0.5	1	mA
		1.5x mode, no load	1	3	8	mA
IQSHDN	Shutdown Current	VEN = 0V			1	µA
ILED-ACC	LED Current Accuracy	1mA ≤ ILED ≤ 31mA		±3	±8	%
ILED-DEV	LED Channel Matching	(ILED - ILEDAVG) / ILEDAVG		±3	±7	%
ROUT	Output Resistance (open loop)	1x mode, IOUT = 100mA		0.4	1	Ω
		1.5x mode, IOUT = 100mA		2.6	7	Ω
FOSC	Charge Pump Frequency		0.8	1	1.3	MHz
ISC_MAX	Output short circuit Current Limit	VOUT < 0.5V	30	60	100	mA
IIN_MAX	Input Current Limit	1x mode, VOUT > 1V	200	300	600	mA
IEN/DIM VHI VLO	EN/DIM Pin Input Leakage		-1		1	µA
	Logic High Level		1.3			V
	Logic Low Level				0.4	V
TSD	Thermal Shutdown		145	165	175	°C
THYS	Thermal Hysteresis		10	20	30	°C
VUVLO	Undervoltage lock out (UVLO) threshold		1.7	2	2.4	V

Recommended EN/DIM Timing

For $3V \leq V_{IN} \leq 5.5V$, over full ambient temperature range -40 to $+85^{\circ}C$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T_{SETP}	EN/DIM setup from shutdown		10			μs
T_{LO}	EN/DIM program low time		0.3		200	μs
T_{HI}	EN/DIM program high time		0.3			μs
T_{OFF}	EN/DIM low time to shutdown		1.5			ms
T_D	LED current enable			40		μs
T_{DEC}	LED current decrement			0.1		μs

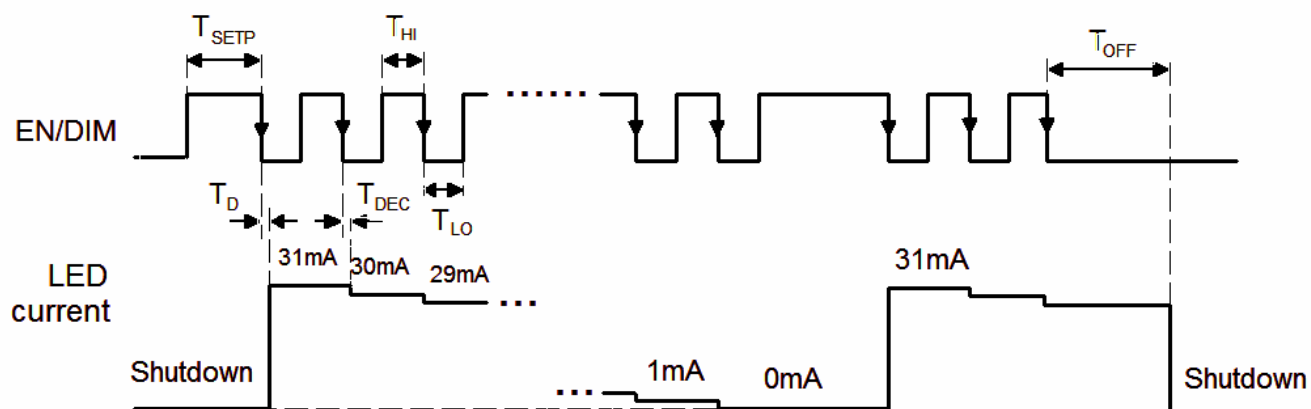
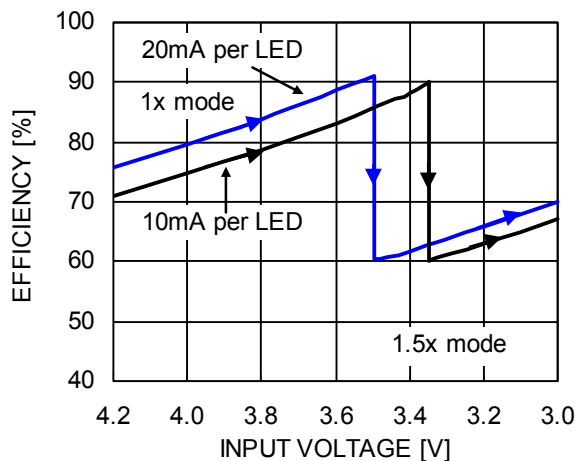


Figure 1. LED Dimming Timing Diagram

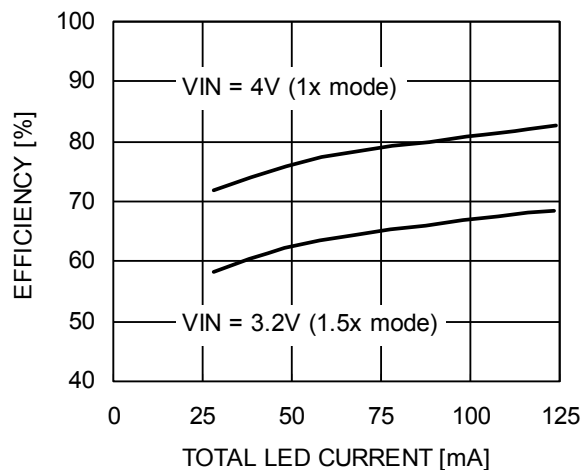
Typical Characteristics

$V_{IN} = 3.6V$, $I_{OUT} = 80mA$ (4 LEDs at 20mA), $C_1 = C_2 = C_{IN} = C_{OUT} = 1\mu F$, $T_{AMB} = 25^\circ C$ unless otherwise specified.

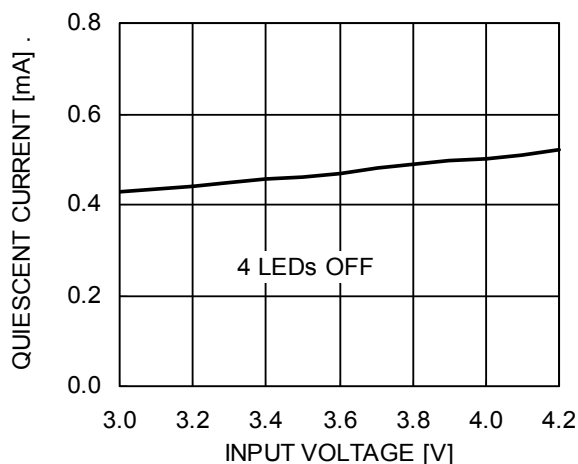
Efficiency vs. Input Voltage (4 LEDs)



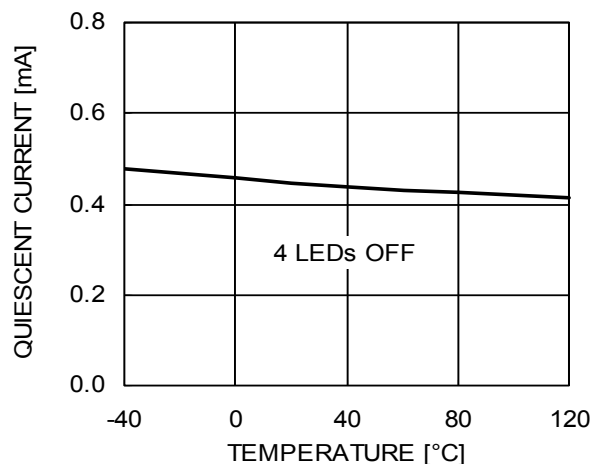
Efficiency vs. Total LED Current (4 LEDs)



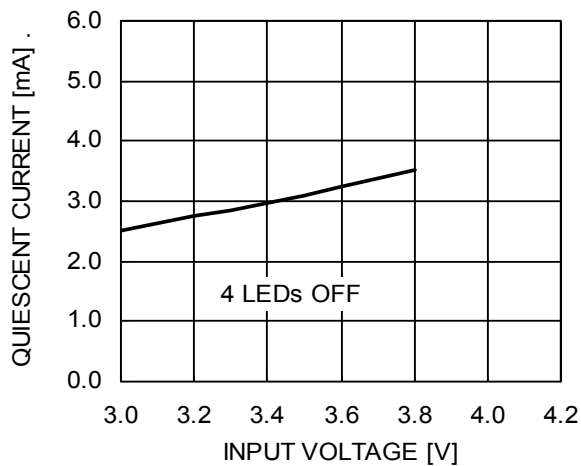
Quiescent Current vs. Input Voltage (1x mode)



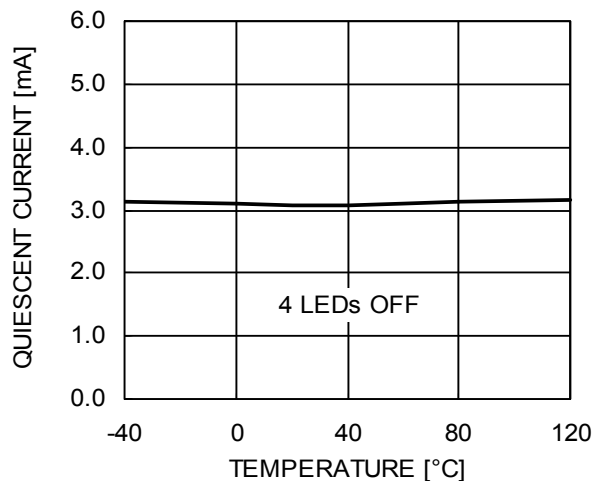
Quiescent Current vs. Temperature (1x mode)



Quiescent Current vs. Input Voltage (1.5x mode)



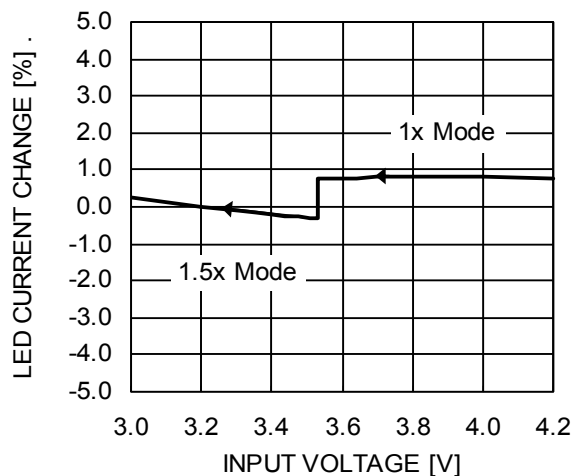
Quiescent Current vs. Temperature (1.5x mode)



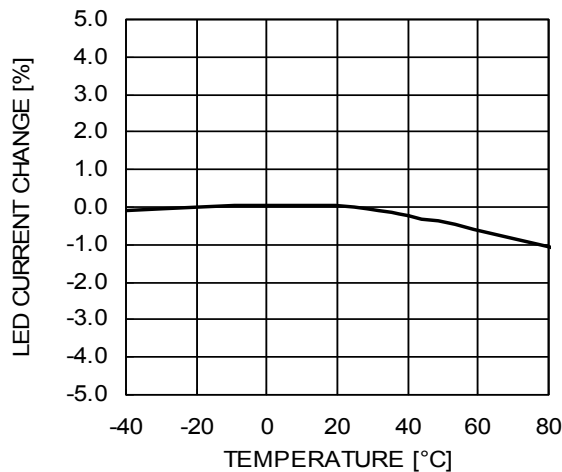
Typical Characteristics

VIN = 3.6V, IOUT = 80mA (4 LEDs at 20mA), C1 = C2 = CIN = COUT = 1μF, TAMB = 25°C unless otherwise specified.

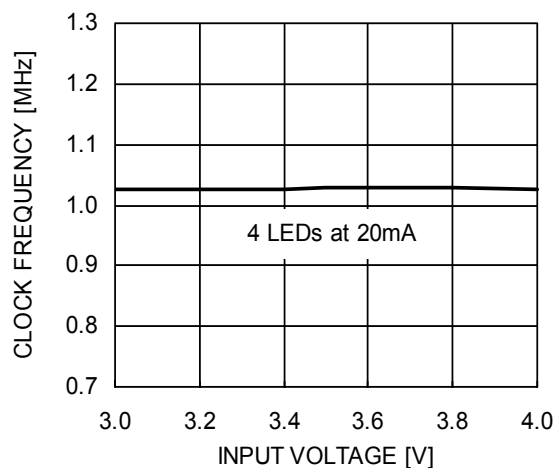
LED Current Change vs. Input Voltage



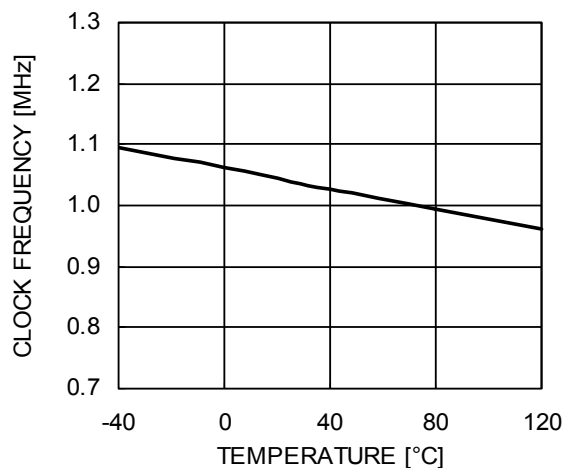
LED Current Change vs. Temperature



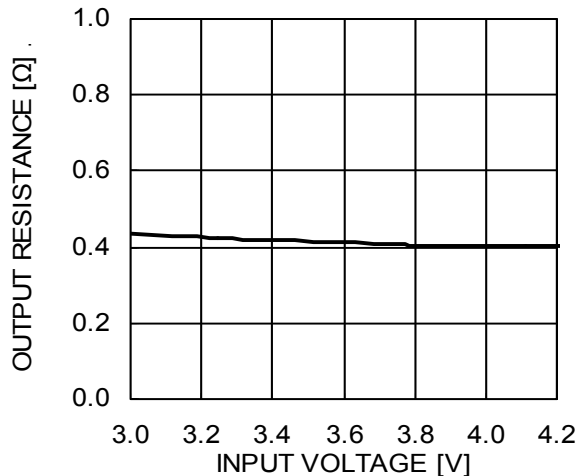
Oscillator Frequency vs. Input Voltage



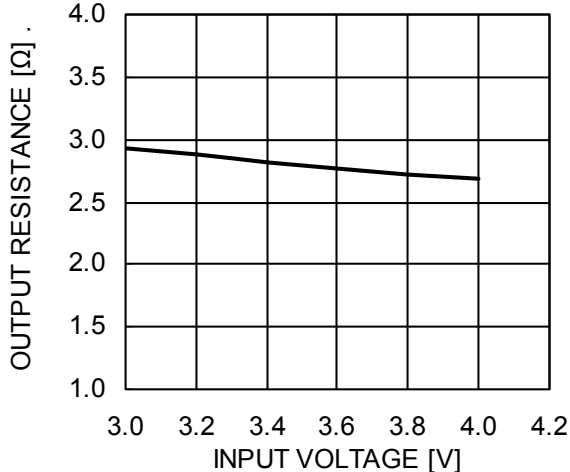
Oscillator Frequency vs. Temperature



Output Resistance vs. Input Voltage (1x mode)



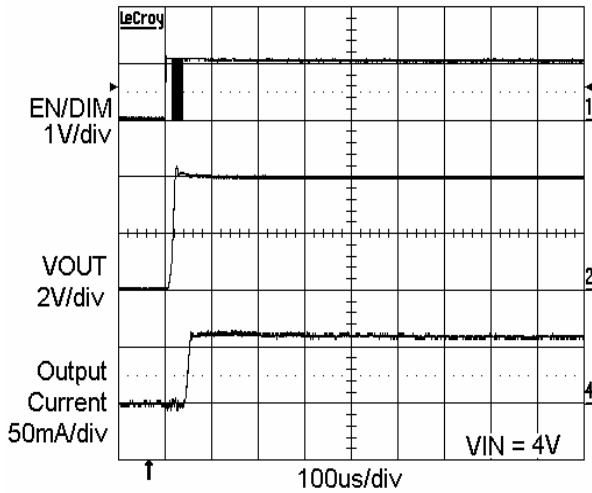
Output Resistance vs. Input Voltage (1.5x mode)



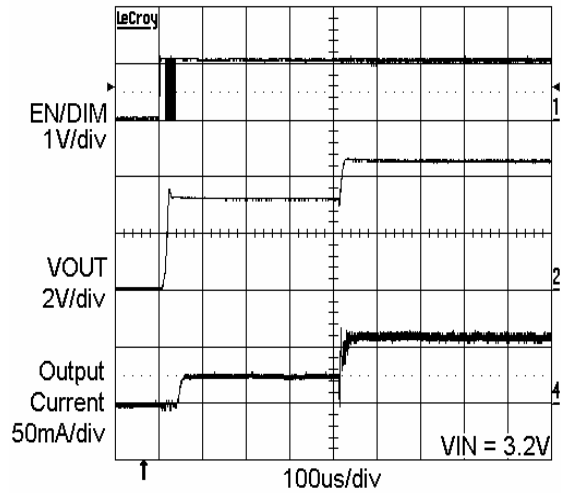
Typical Characteristics

VIN = 3.6V, IOUT = 80mA (4 LEDs at 20mA), C1 = C2 = CIN = COUT = 1μF, TAMB = 25°C unless otherwise specified.

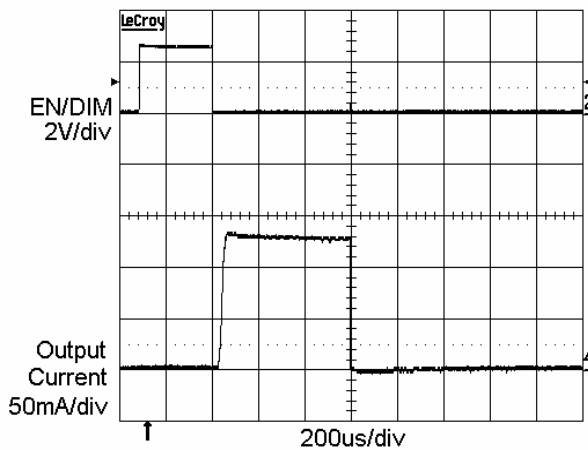
Power Up with 4 LEDs at 15mA (1x Mode)



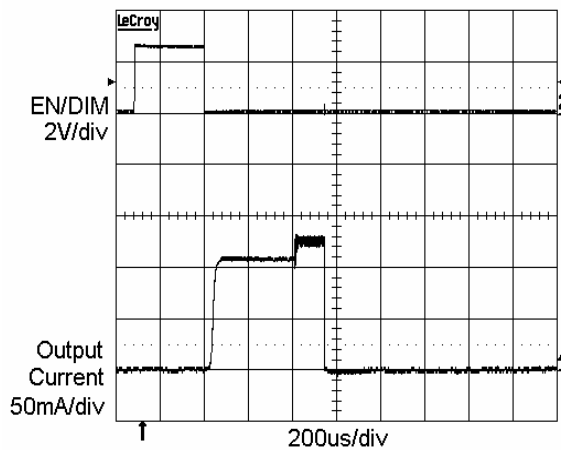
Power Up with 4 LEDs at 15mA (1.5x Mode)



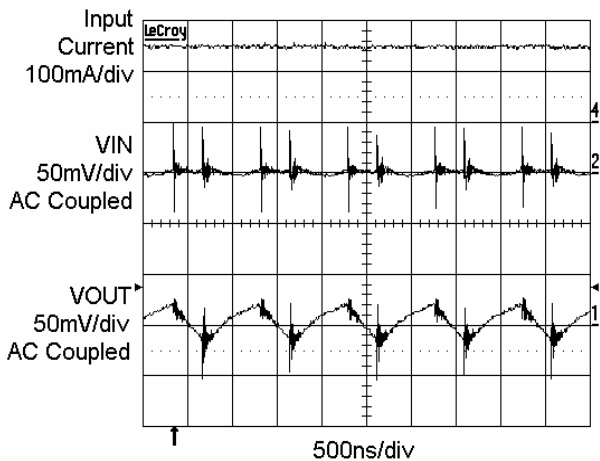
Enable Power Down Delay (1x Mode)



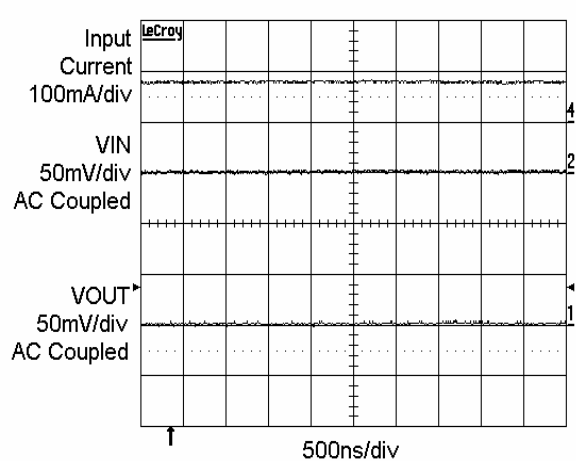
Enable Power Down Delay (1.5x Mode)



Switching Waveforms in 1.5x Mode



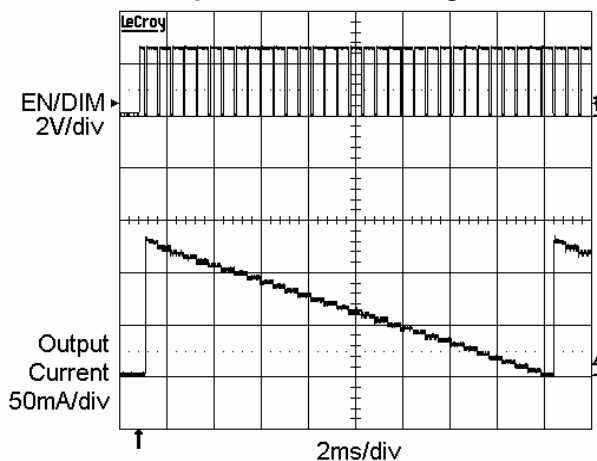
Operating Waveforms in 1x Mode



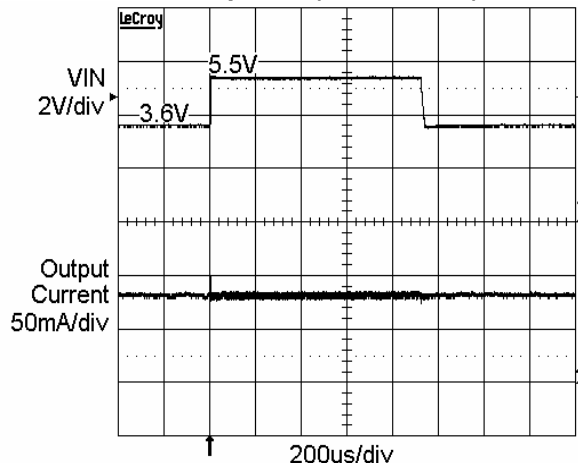
Typical Characteristics

VIN = 3.6V, IOUT = 80mA (4 LEDs at 20mA), C1 = C2 = CIN = COUT = 1μF, TAMB = 25°C unless otherwise specified.

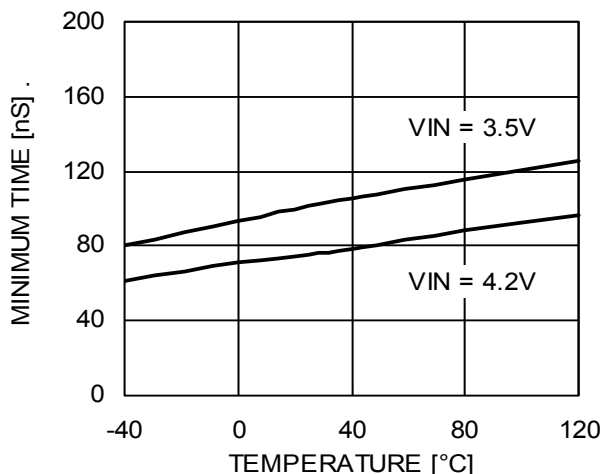
Enable and Output Current Dimming Waveforms



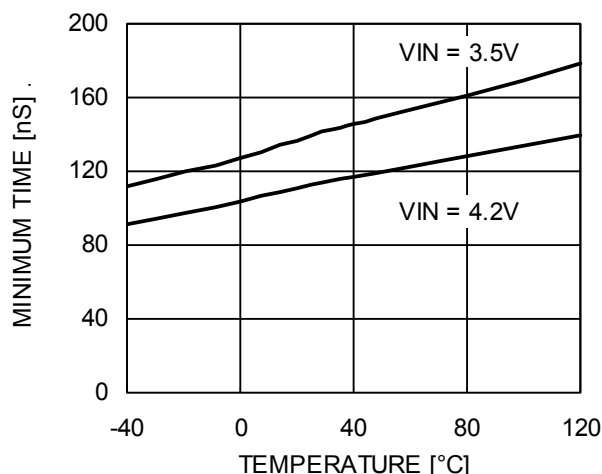
Line Transient Response (3.6V to 5.5V) 1x Mode



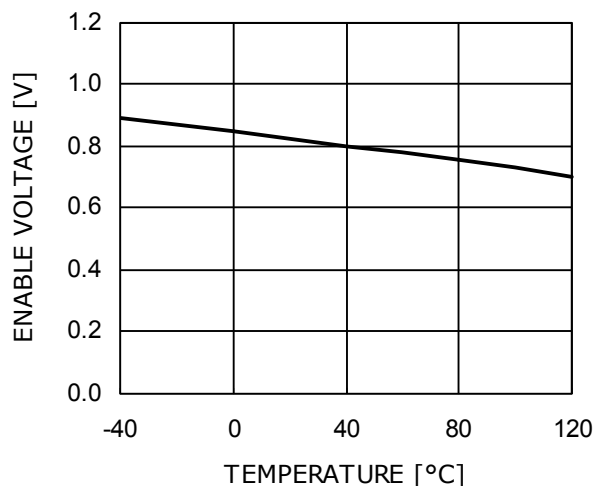
Enable High Minimum Program Time vs. Temperature



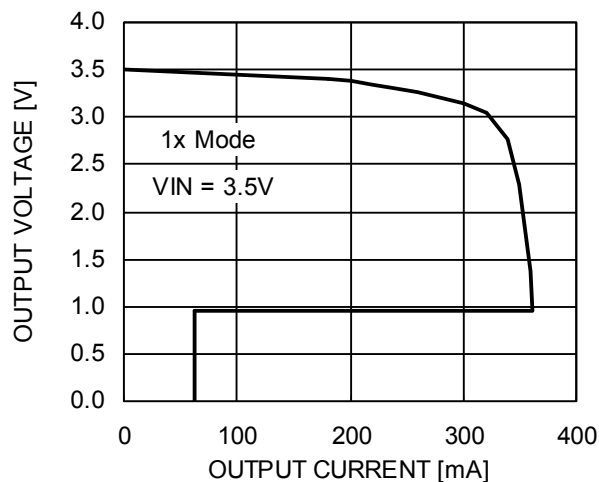
Enable Low Minimum Program Time vs. Temperature



Enable Voltage Threshold vs. Temperature



Foldback Current Limit



PIN DESCRIPTIONS

Pin #	Name	Function
1	VIN	Supply voltage.
2	C1+	Bucket capacitor 1 terminal
3	C1-	Bucket capacitor 1 terminal
4	C2-	Bucket capacitor 2 terminal
5	C2+	Bucket capacitor 2 terminal
6	GND	Ground reference
7	LED1	LED1 cathode terminal (if not used, connect to VOUT) ¹
8	LED2	LED2 cathode terminal (if not used, connect to VOUT) ¹
9	LED3	LED3 cathode terminal (if not used, connect to VOUT) ¹
10	LED4	LED4 cathode terminal (if not used, connect to VOUT) ¹
11	EN/DIM	Device enable (active high) and dimming control input
12	VOUT	Charge pump output connected to the LED anodes
TAB	TAB	Connect to GND on the PCB

Note:

(1) LED1, LED2, LED3, LED4 pins should not be left floating. They should be connected to the LED cathode, or tied to VOUT pin if not used.

PIN FUNCTION

VIN is the supply pin for the charge pump. A small 1 μ F ceramic bypass capacitor is required between the VIN pin and ground near the device. The operating input voltage range is from 2.2V to 5.5V. Whenever the input supply falls below the undervoltage threshold (2V) all LEDs channels will be automatically disabled.

EN/DIM is the enable and dimming control logic input for all LED channels. Guaranteed levels of logic high and logic low are set at 1.3V and 0.4V respectively. When EN/DIM is initially taken high, the device becomes enabled and all LED currents remain at 0mA. The falling edge of the first pulse applied to EN/DIM sets all LED currents to their full scale of 31mA.

On each consecutive falling edge of the pulse applied to EN/DIM, the LED current is decreased by 1mA step. On the 32nd pulse, the LED current is set to zero. The next pulse on EN/DIM resets the current back to their full scale of 31mA.

To place the device into zero current shutdown mode, the EN/DIM pin must be held low for 1.5ms or more.

VOUT is the charge pump output that is connected to the LED anodes. A small 1 μ F ceramic bypass capacitor is required between the VOUT pin and ground near the device.

GND is the ground reference for the charge pump. The pin must be connected to the ground plane on the PCB.

C1+, C1- are connected to each side of the 1 μ F ceramic bucket capacitor C1.

C2+, C2- are connected to each side of the 1 μ F ceramic bucket capacitor C2.

LED1 to LED4 provide the internal regulated current for each of the LED cathodes. These pins enter a high impedance zero current state whenever the device is placed in shutdown mode. In applications using less than four LEDs, all unused channels should be wired directly to VOUT. This ensures the channel is automatically disabled dissipating less than 200 μ A.

TAB is the exposed pad underneath the package. For best thermal performance, the tab should be soldered to the PCB and connected to the ground plane.

BLOCK DIAGRAM

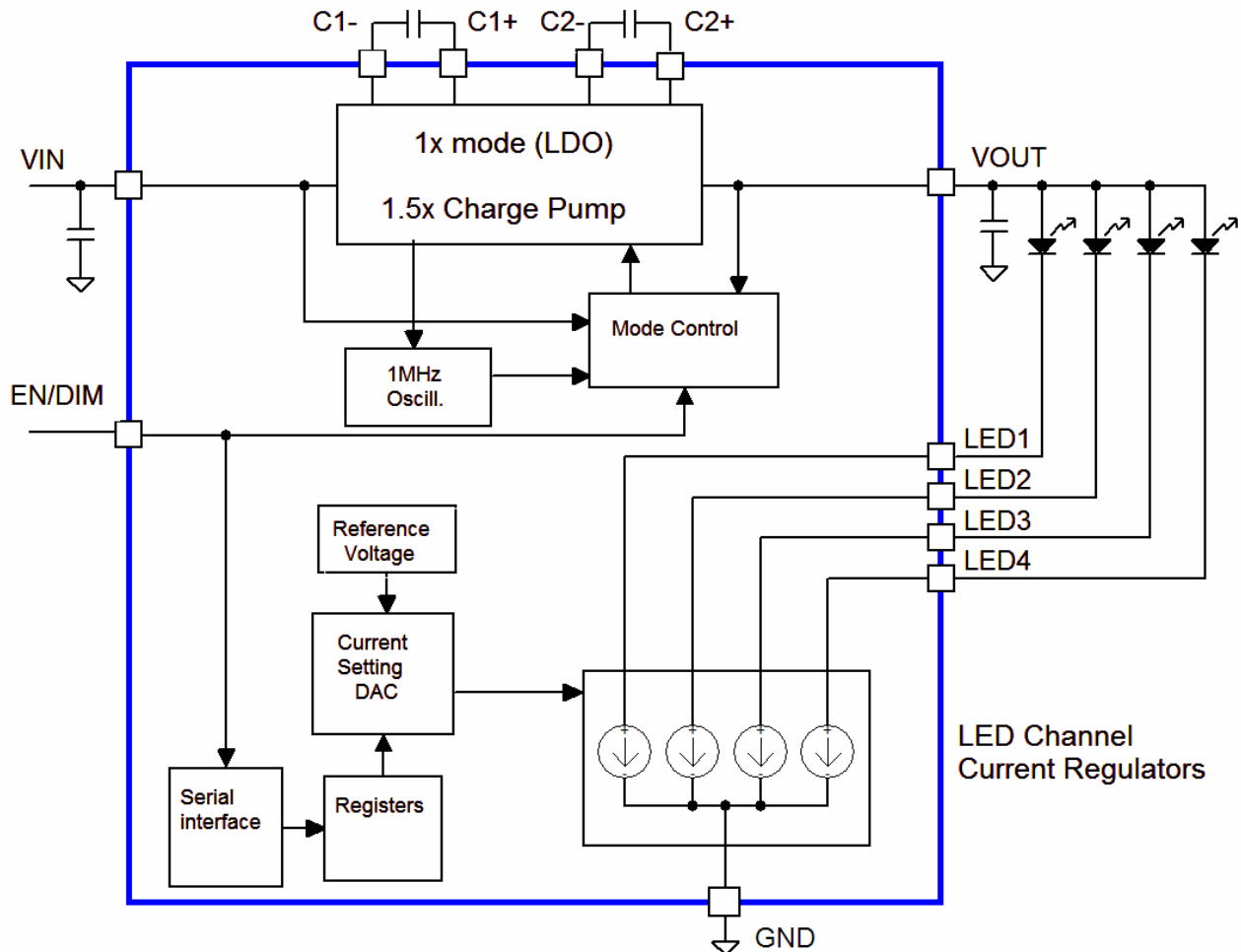


Figure 2. CAT3614 Functional Block Diagram

BASIC OPERATION

At power-up, the CAT3614 starts operating in 1x mode where the output will be approximately equal to the input supply voltage (less any internal voltage losses). If the output voltage is sufficient to regulate all LED currents the device remains in 1x operating mode.

If the input voltage is insufficient or falls to a level where the regulated currents cannot be maintained, the device automatically switches (after a fixed delay of 400µs) into 1.5x mode.

In 1.5x mode, the output is approximately equal to 1.5 times the input supply voltage (less any internal voltage losses).

The above sequence is repeated each and every time the chip is powered-up or is taken out of shutdown mode (via EN/DIM pin).

LED Current Setting

Figure 1 shows the timing diagram necessary at the EN/DIM input for setting the LED currents.

The EN/DIM set up time requires the signal to be held high for 10 μ s or longer to ensure the initialization of the driver at power-up. Each subsequent pulse on the EN/DIM (300ns to 200 μ s pulse duration) steps down the LED current from full scale of 31mA to zero with a 1mA resolution. Consecutive pulses should be separated by 300ns or longer. Pulsing beyond the 0mA level restores the current level back to full scale and the cycle repeats. Pulsing frequencies from 5kHz up to 1MHz can be supported during dimming operations. When the EN/DIM is held low for 1.5ms or more, the CAT3614 enters the shutdown mode and draws “zero” current.

For applications with three LEDs or less, any unused LED pins should be tied to VOUT, as shown on Figure 3.

Protection Mode

If an LED becomes open-circuit, the output voltage VOUT is internally limited to about 5.5V. This is to prevent the output pin from exceeding its absolute maximum rating.

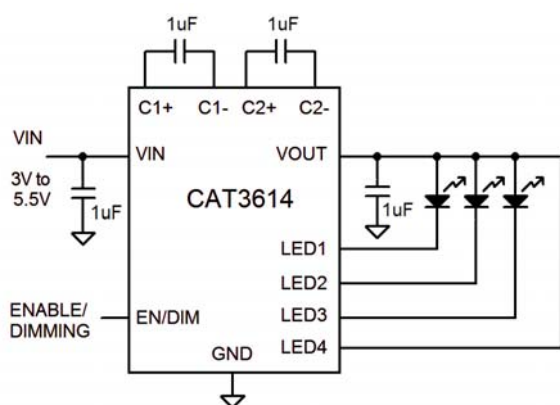


Figure 3. Three LED Application

The driver enters a thermal shutdown mode as soon as the die temperature exceeds about +165°C. When the device temperature drops down by about 20°C, the device resumes normal operation.

External Components

The driver requires a total of four external 1 μ F ceramic capacitors: two for decoupling input and output, and two for the charge pump. Both capacitor types X5R and X7R are recommended for the LED driver application. In the 1.5x charge pump mode, the input current ripple is kept very low by design, and an input bypass capacitor of 1 μ F is sufficient. In 1x mode, the device operating in linear mode does not introduce switching noise back onto the supply.

Recommended Layout

In 1.5x charge pump mode, the driver switches internally at a high frequency of 1MHz. It is recommended to minimize trace length to all four capacitors. A ground plane should cover the area under the driver IC as well as the bypass capacitors. Short connection to ground on capacitors Cin and Cout can be implemented with the use of multiple vias. A copper area matching the TDFN exposed pad (GND) must be connected to the ground plane underneath. The use of multiple vias improves the package heat dissipation.

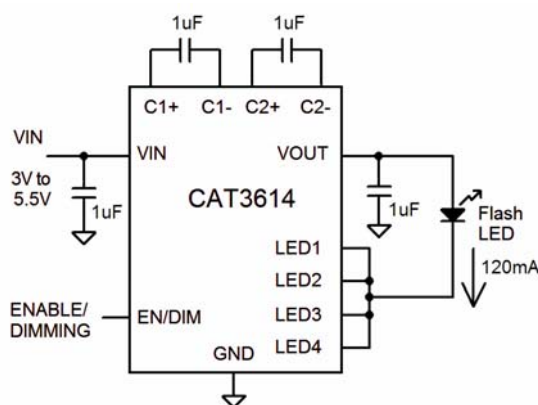
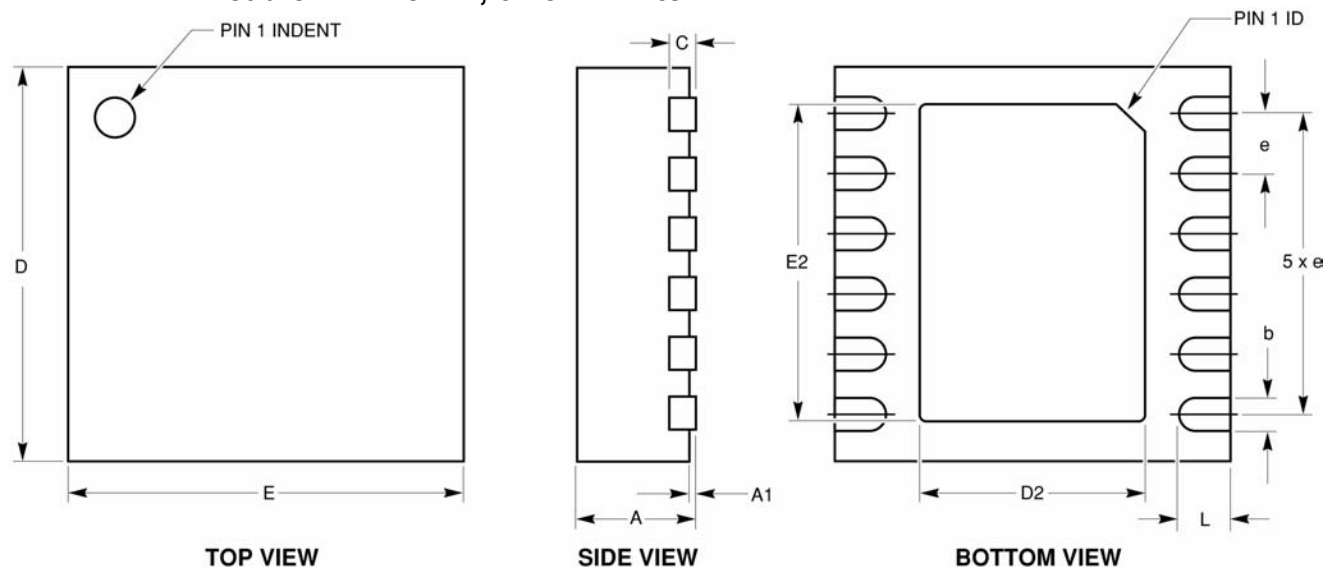


Figure 4. Single Flash LED Application

PACKAGE DRAWING AND DIMENSIONS

Thin DFN 12-Lead 3mm X 3mm, 0.45mm Pitch



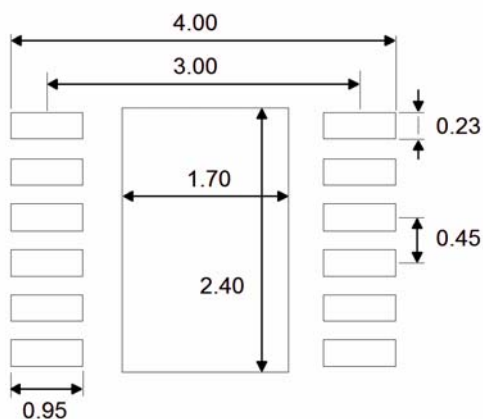
SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.18	0.23	0.30
C		0.20 REF	
D	2.90	3.00	3.10
D2	1.60	1.70	1.80
E	2.90	3.00	3.10
E2	2.30	2.40	2.50
e		0.45	
L	0.35	0.45	0.55

NOTE:
1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
2. REFER JEDEC MO-229

TDFN-12L-3X3_02) .eps

RECOMMENDED LAND PATTERN

Dimensions in millimeters



REVISION HISTORY

Date	Rev.	Reason
02/09/2006	00	Initial Release
07/21/06	01	Update Typical Application Circuit Update Pin Descriptions Update Electrical Operating Characteristics

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